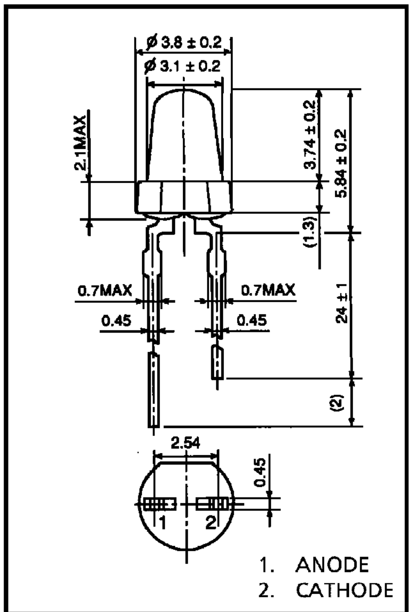
TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

TLGD160

PANEL CIRCUIT INDICATOR

Unit in mm



JEDEC	—
EIAJ	—
TOSHIBA	4-3E1A

Weight : 0.12g

- All Plastic Mold Type
  Clear Transparent Lens
- Low Drive Current, High Intensity Green Light Emission.
  Recommended Forward Current : $I_F = 15 \sim 20$mA (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	I_F	40	mA
Reverse Voltage	V_R	4	V
Power Dissipation	P_D	120	mW
Operating Temperature Range	T_{opr}	−20~85	°C
Storage Temperature Range	T_{stg}	−30~100	°C

ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage		V_F	$I_F = 20$mA	—	2.15	2.8	V
Reverse Current		I_R	$V_R = 4$V	—	—	5	μA
Luminous Intensity	TLGD160	I_V	$I_F = 20$mA (Note)	140	300	—	mcd
	TLGD160 (PQ)			153	—	736	
Peak Emission Wave Length		λ_p	$I_F = 20$mA	—	567	—	nm
Spectral Line Half Width		$\Delta\lambda$	$I_F = 20$mA	—	25	—	nm

(Note) Rank selection carried out under next standard range respectively, although it needs ±15% sdditionary for guaranteed limits.
P : 180-360mcd Q : 320-640mcd
Each rank products is classified by package unit, and (PQ) includes P and Q.

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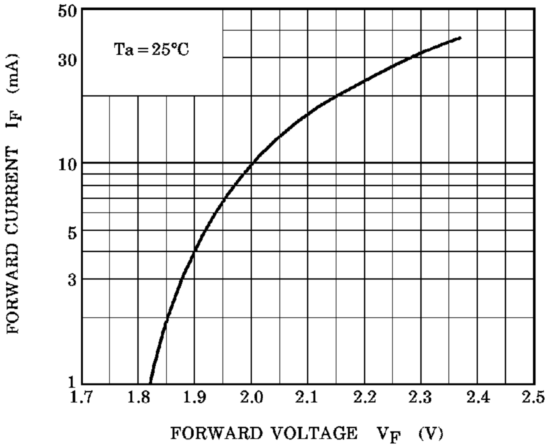
PRECAUTION

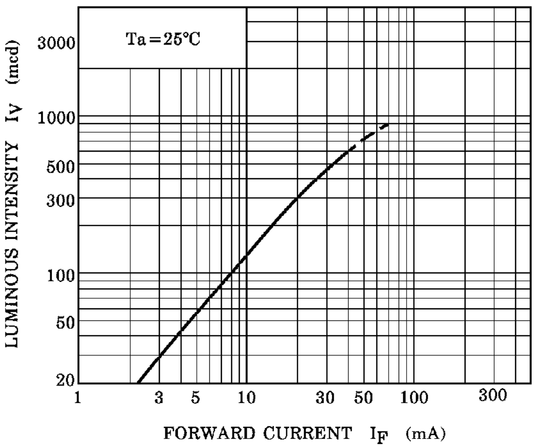
Please be careful of the followings.

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
  (Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.

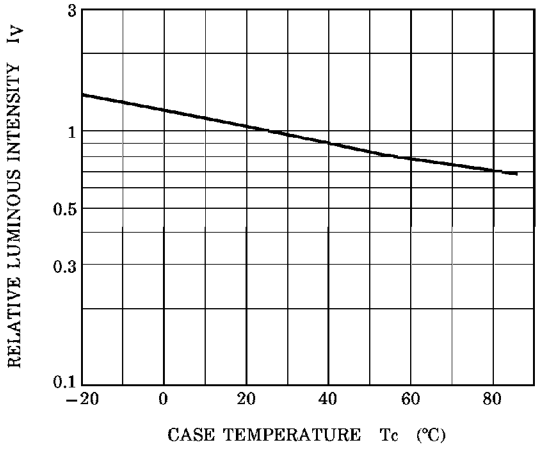
I_F – V_F



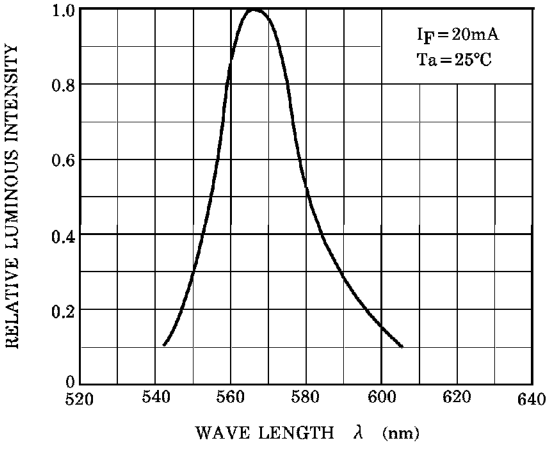
I_V – I_F



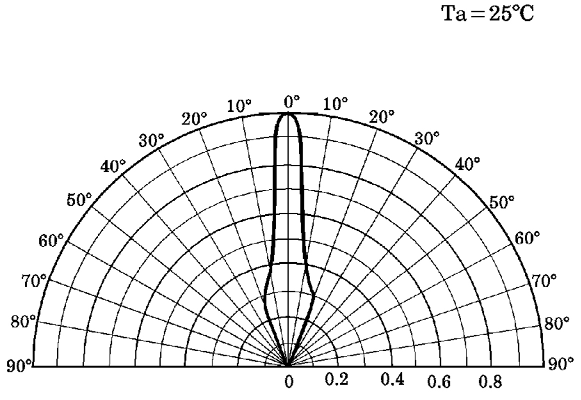
I_V – Tc



RELATIVE LUMINOUS INTENSITY – WAVE LENGTH



RADIATION PATTERN



I_F – Ta